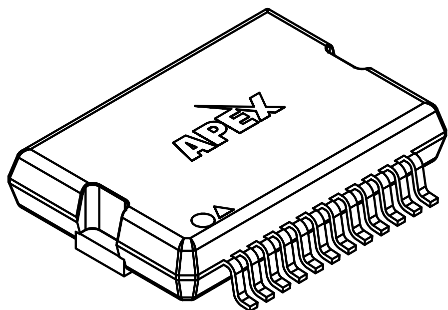
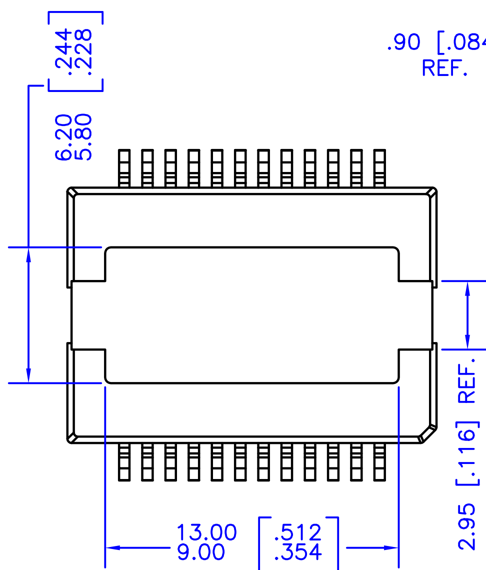
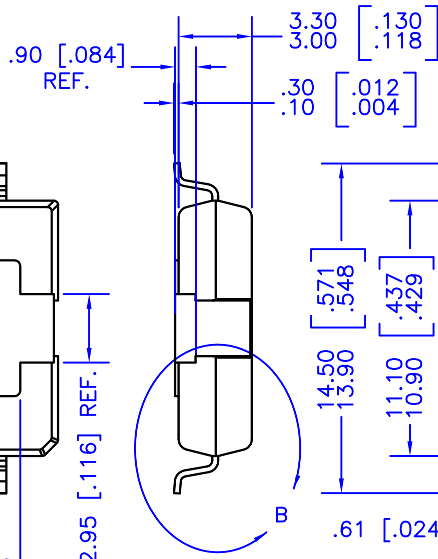
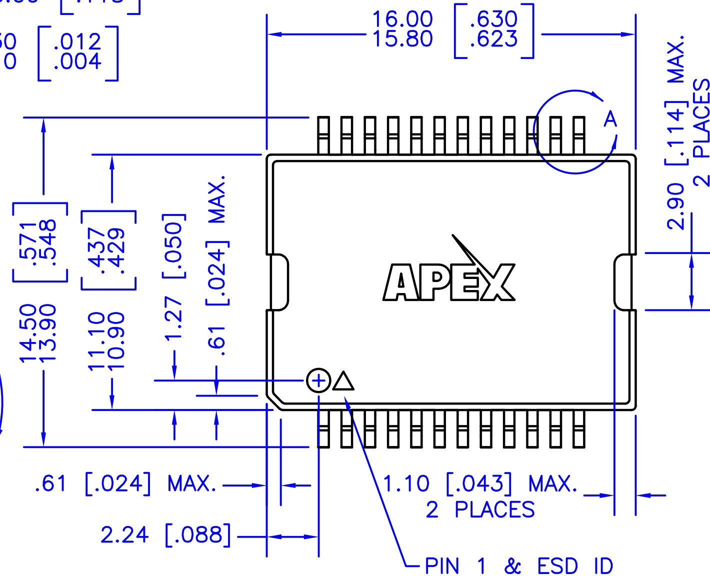
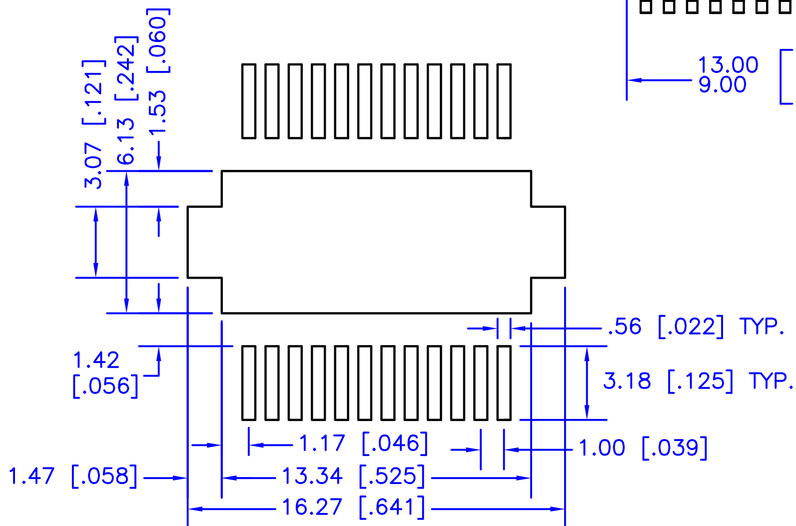


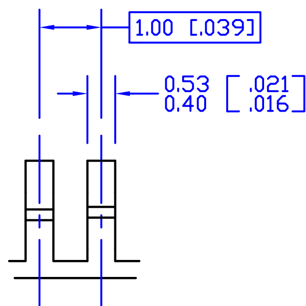






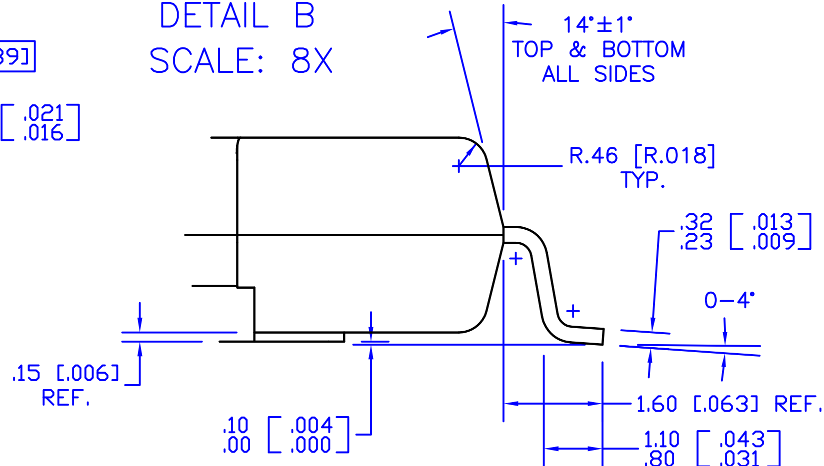


Surface Mount Layout



DETAIL A
SCALE: 8X

DETAIL B
SCALE: 8X



NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Dimple on lid & ESD triangle denote pin 1.
4. Pins & Heat Slug: CDA 194 copper with bismuth solder finish
5. Mold compound: MP–8000AN epoxy
6. Package weight: .086 oz. [2.44 g]
7. Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED
.XX = ±.01 [.254]
.XXX = ±.005 [.127]
ANG. = ±5°

TITLE:	JEDEC MO-166, 24-pin PSOP	MODEL:	DF
SUBJECT:	PACKAGE OUTLINE		

ENGINEER:	DRAWN BY:	DCA:	SH.	OF	FILENAME:	REV:	DATE:
D-M	R.MORG	13227	1	1	DF	E	29MAY13